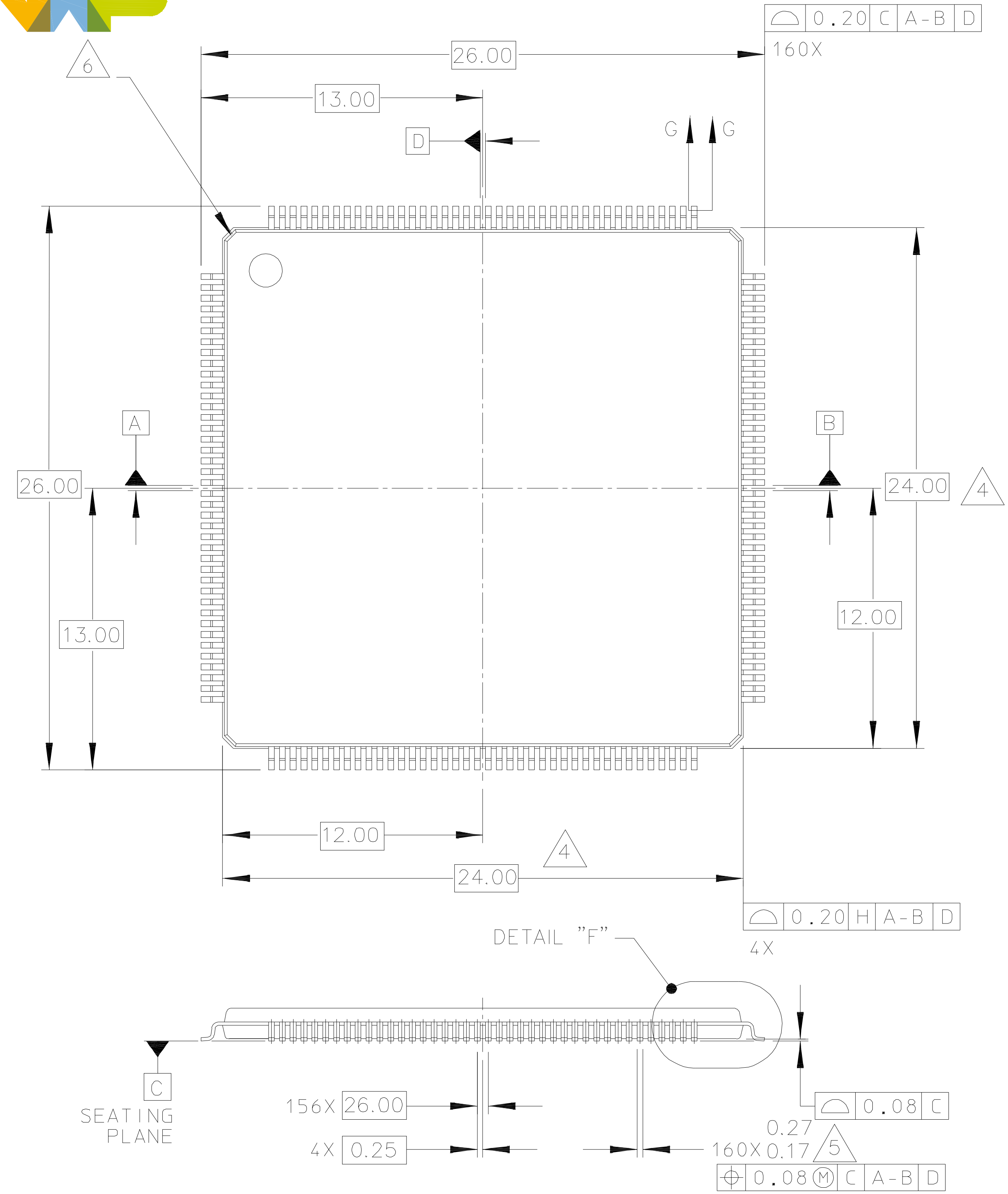

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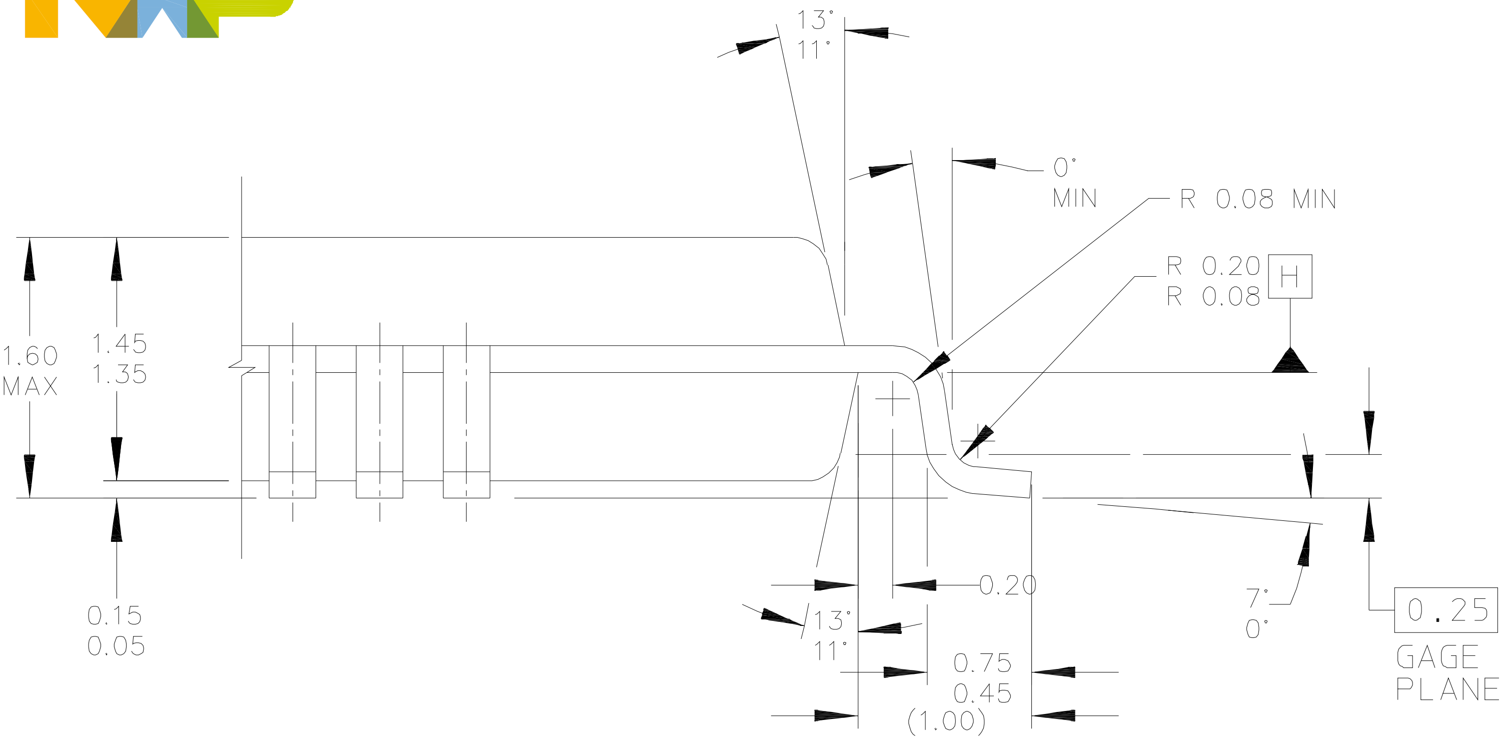
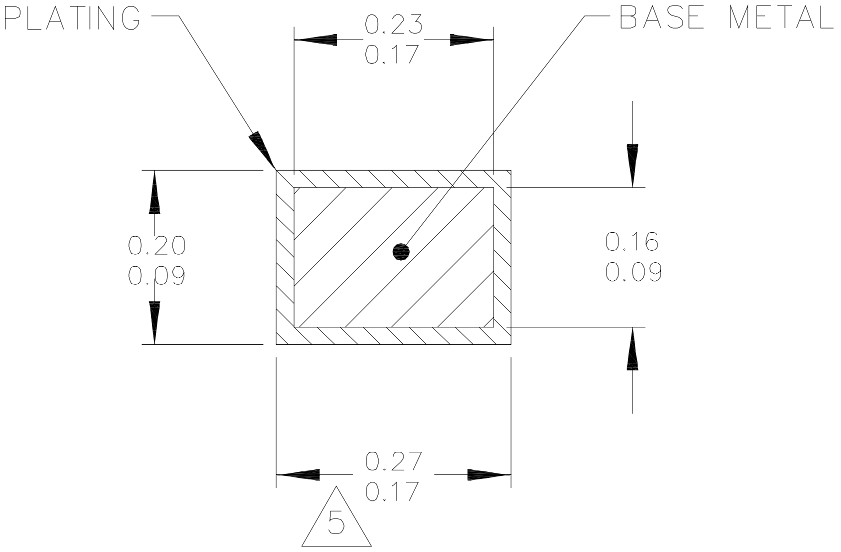
TITLE: QUAD FLAT PACKAGE (LQFP) 160 LEAD, 0.50 PITCH 24.00 X 24.00 X 1.40	DOCUMENT NO: 98ASH98073A REV: C
	STANDARD: NON-JEDEC
	SOT435-2 25 JAN 2016



DETAIL F



SECTION G–G

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TITLE: QUAD FLAT PACKAGE (LQFP) 160 LEAD, 0.50 PITCH 24.00 X 24.00 X 1.40	DOCUMENT NO: 98ASH98073A REV: C	
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	SOT435-2 25 JAN 2016	

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.

3. DATUMS A, B AND D TO BE DETERMINED WHERE THE LEADS EXIT THE PLASTIC BODY AT DATUM PLANE H.

4. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 MM PER SIDE. DIMENSIONS ARE MAXIMUM PLASTIC BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.

5. DIMENSIONS DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE MAXIMUM DIMENSION BY MORE THAN 0.08 MM. DAMBAR CAN NOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN A PROTRUSION AND AN ADJACENT LEAD IS 0.07 MM.

6. EXACT SHAPE OF CORNERS MAY VARY.

MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE: QUAD FLAT PACKAGE (LQFP)
160 LEAD, 0.50 PITCH
24.00 X 24.00 X 1.40

DOCUMENT NO: 98ASH98073A REV: C

STANDARD: NON-JEDEC

SOT435-2 25 JAN 2016